THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction−to−Lead (Note 1)	$R_{\theta JL}$	24	°C/W
Thermal Resistance, Junction−to−Ambient (Note 2)	$R_{\theta JA}$	80	

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 3)		v_F	**T_J = 25°C**	**T_J = 125°C**	V
see Figure 2	(i_F = 1.5 A)		0.46	0.39	
	(i_F = 3.0 A)		0.54	0.54	
Maximum Instantaneous Reverse Current (Note 3)		I_R	**T_J = 25°C**	**T_J = 100°C**	mA
see Figure 4	(V_R = 40 V)		0.8	5.7	
	(V_R = 20 V)		0.1	1.6	

1. Mounted with minimum recommended pad size, PC Board FR4.
2. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.
3. Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2.0%.

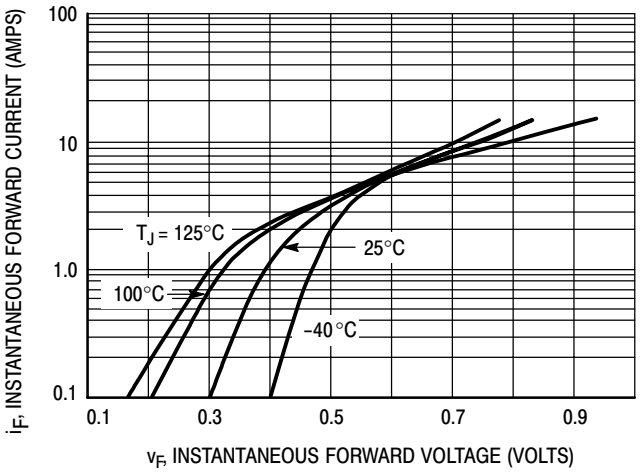


Figure 1. Typical Forward Voltage

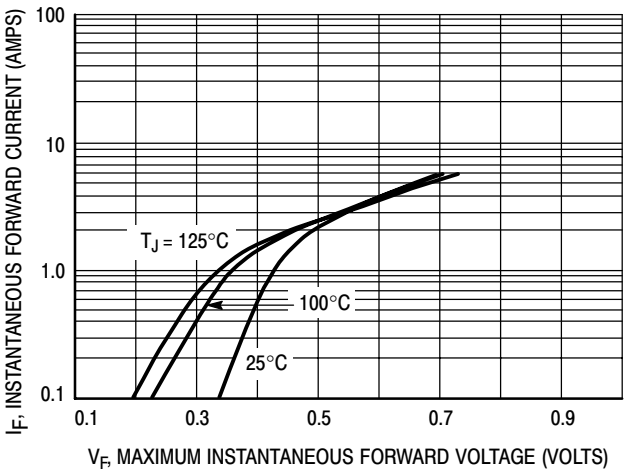


Figure 2. Maximum Forward Voltage

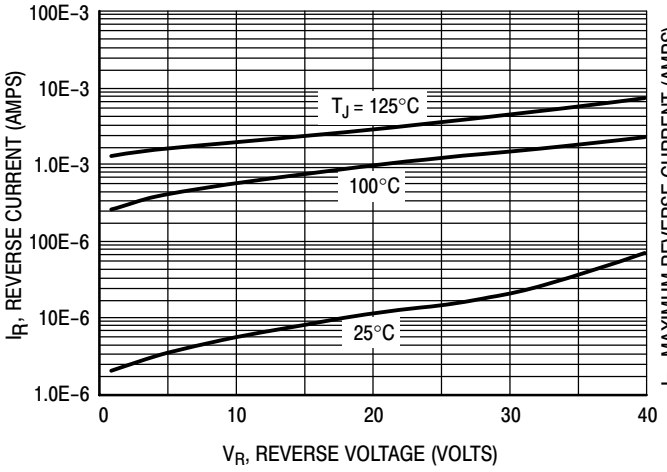


Figure 3. Typical Reverse Current

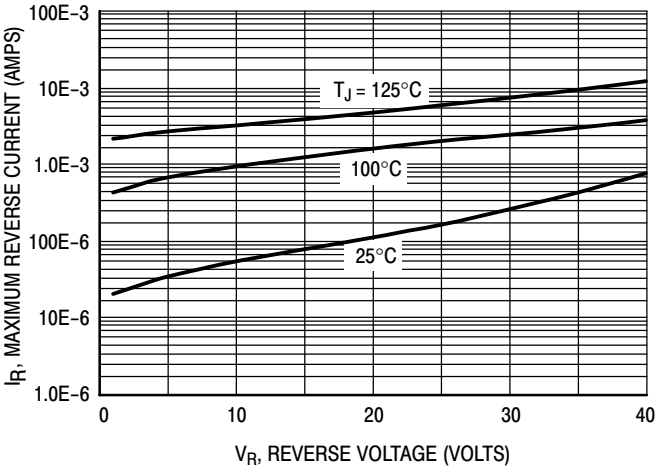


Figure 4. Maximum Reverse Current

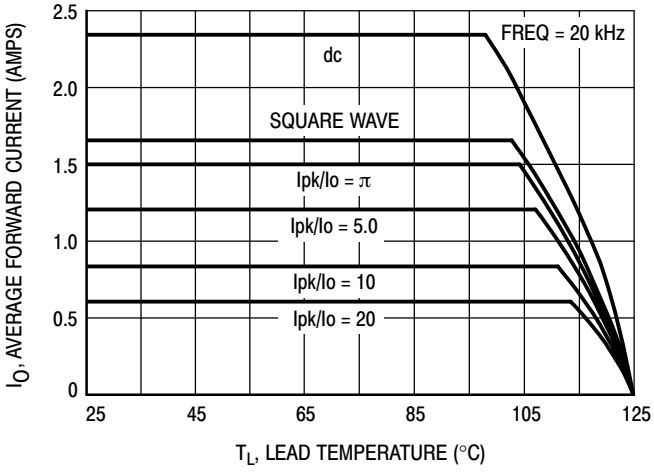


Figure 5. Current Derating

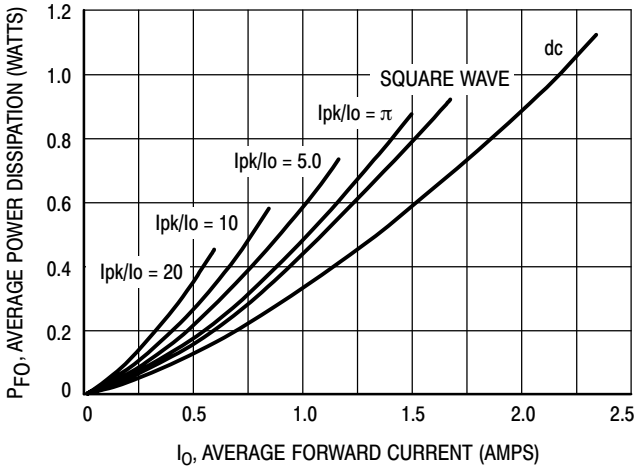


Figure 6. Forward Power Dissipation

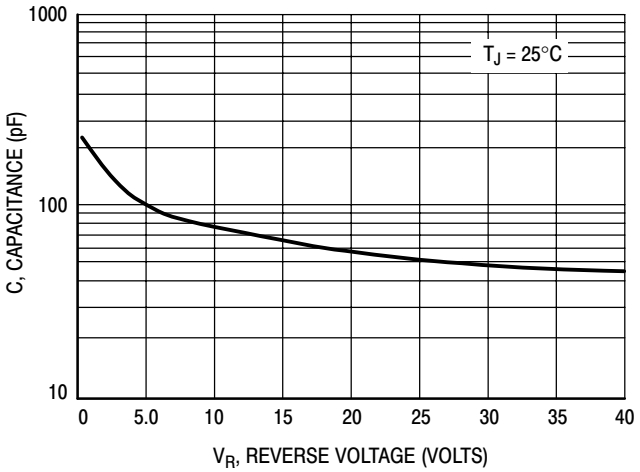


Figure 7. Capacitance

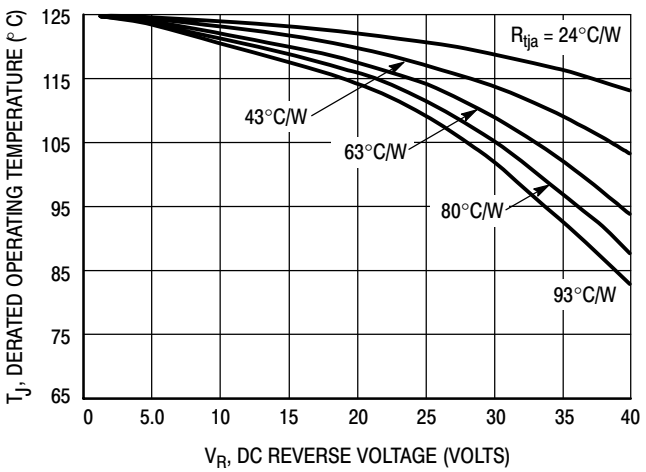


Figure 8. Typical Operating Temperature Derating*

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where

r(t) = thermal impedance under given conditions,
Pf = forward power dissipation, and
Pr = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where r(t) = Rthja. For other power applications further calculations must be performed.

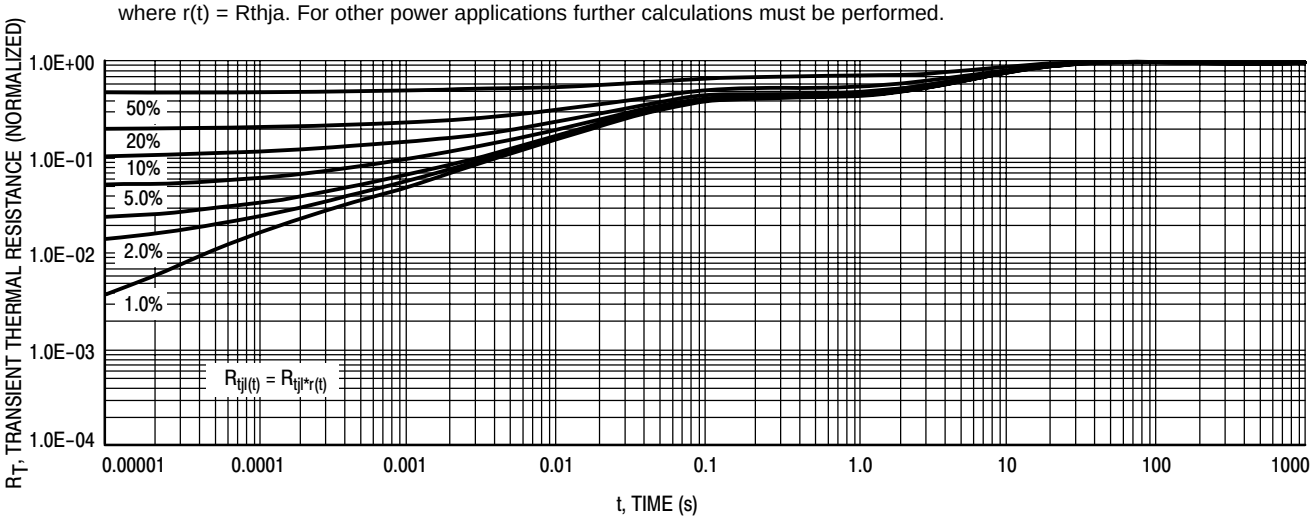


Figure 9. Thermal Response — Junction to Case

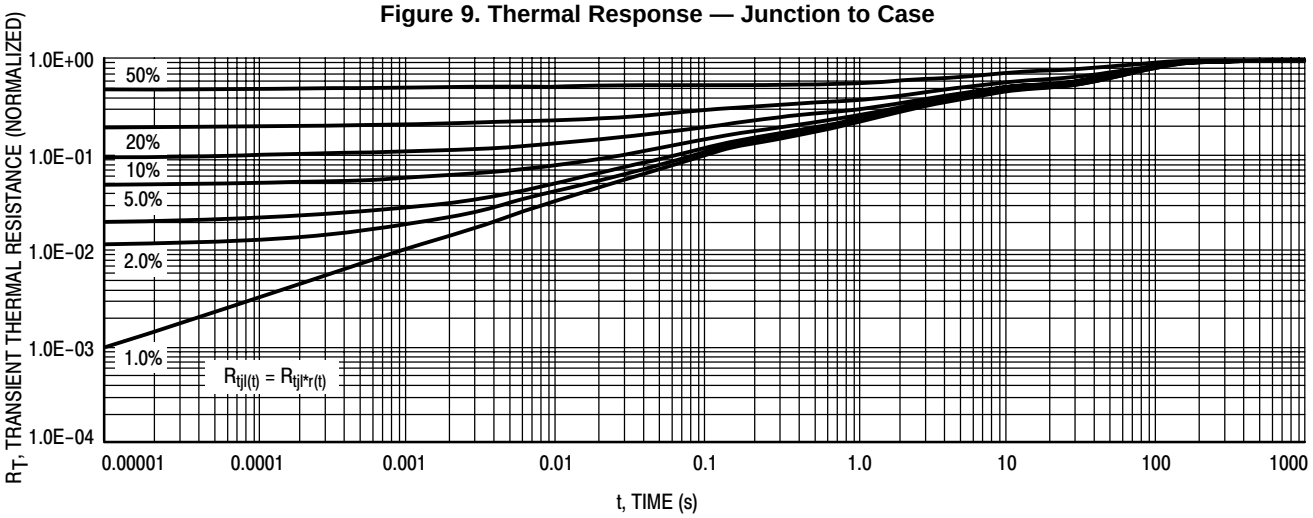
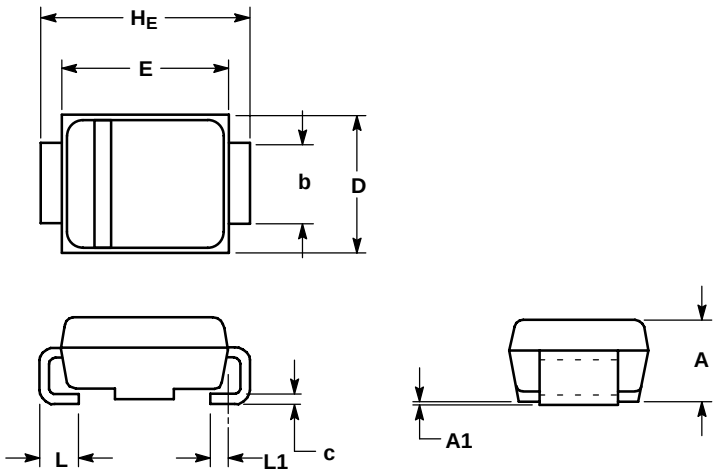


Figure 10. Thermal Response — Junction to Ambient

MBRS1540T3

PACKAGE DIMENSIONS

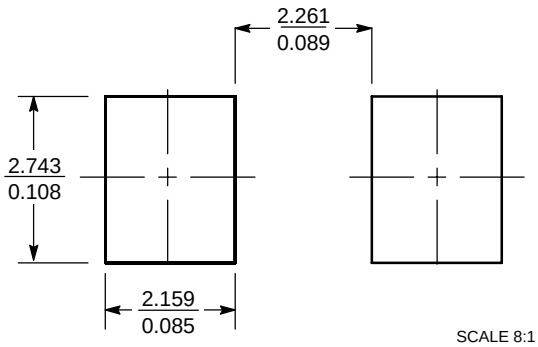
SMB
PLASTIC PACKAGE
CASE 403A−03
ISSUE E



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	1.90	2.13	2.41	0.075	0.084	0.095
A1	0.05	0.10	0.15	0.002	0.004	0.006
b	1.96	2.03	2.11	0.077	0.080	0.083
c	0.15	0.23	0.30	0.006	0.009	0.012
D	3.30	3.56	3.81	0.130	0.140	0.150
E	4.06	4.32	4.57	0.160	0.170	0.180
H_E	5.21	5.44	5.59	0.205	0.214	0.220
L	0.76	1.02	1.27	0.030	0.040	0.050
L1	0.51 REF			0.020 REF		

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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